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TITLE: Adhesive sheet for semiconductor wafer processing

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ABSTRACT:

CHG DATE=19990617 STATUS=O> The sheet comprises a substrate having coated on the surface thereof an adhesive layer which comprises an adhesive (e.g. an acrylate ester polymer) and a radiation polymerizable compound (e.g. a urethane acrylate oligomer), and is characterized in that the substrate is a synthetic resin film having carboxyl-containing monomer units, e.g. a film of ethylene-(meth) acrylic acid copolymer. The sheet is used to hold semiconductor wafers while they are diced to form chips. Before pick-up the adhesive layer is irradiated (e.g. with UV or electron beam radiation) to reduce its adhesiveness so that no adhesive remains attached to the chips after pick-up.